

10 9 8 7 6 5 4 3 2 1

F

F

E

E

D

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C

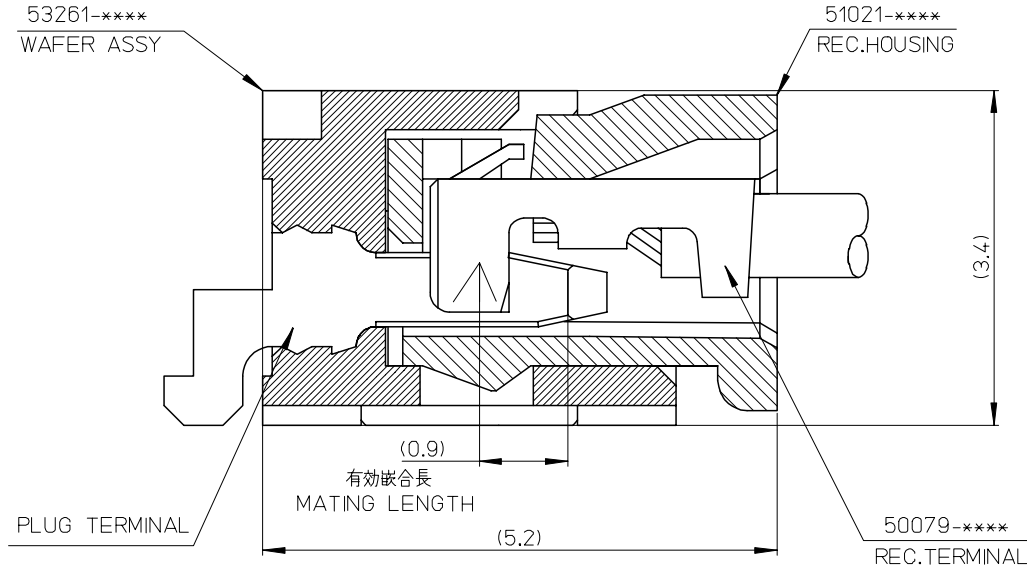
C

B

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A



53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN: A0YAGI 2006/02/02 CHKD: YMAEDA 2006/02/03 APPR: NUKITA 2006/02/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY Y. A0YAGI	DATE 2006/01/30	TITLE 1.25 W-TO-B CONN. 51021,53261 MATING CROSS SECTION			
	10 OVER 30 UNDER	± ---	CHECKED BY Y. MAEDA	DATE 2006/01/30	MOLEX INCORPORATED			
	30 OVER	± ---	APPROVED BY N. UKITA	DATE 2006/01/30	DOCUMENT NO. SD-51021-002			
	ANGULAR	± --- °	MATERIAL NO. SEE CHART		SHEET NO. 1 OF 1			
0	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

9

8

7

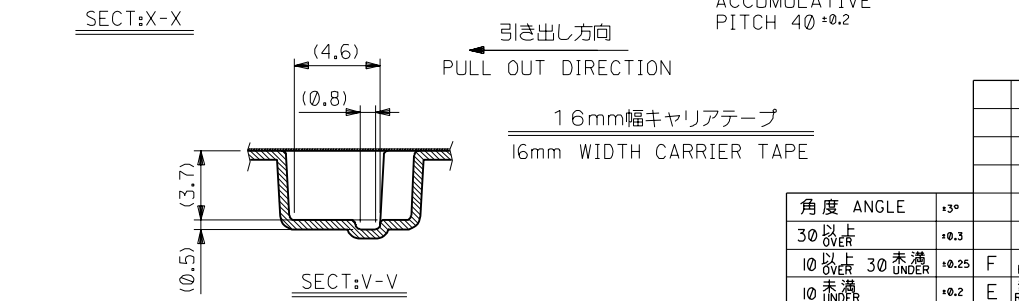
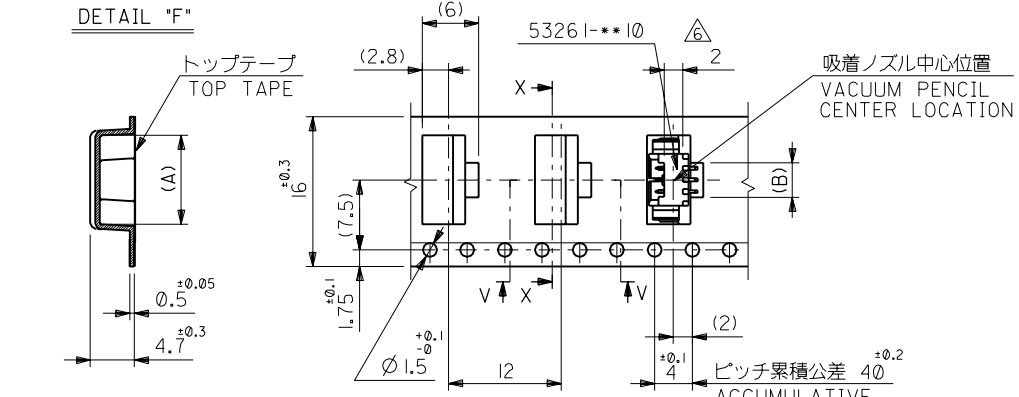
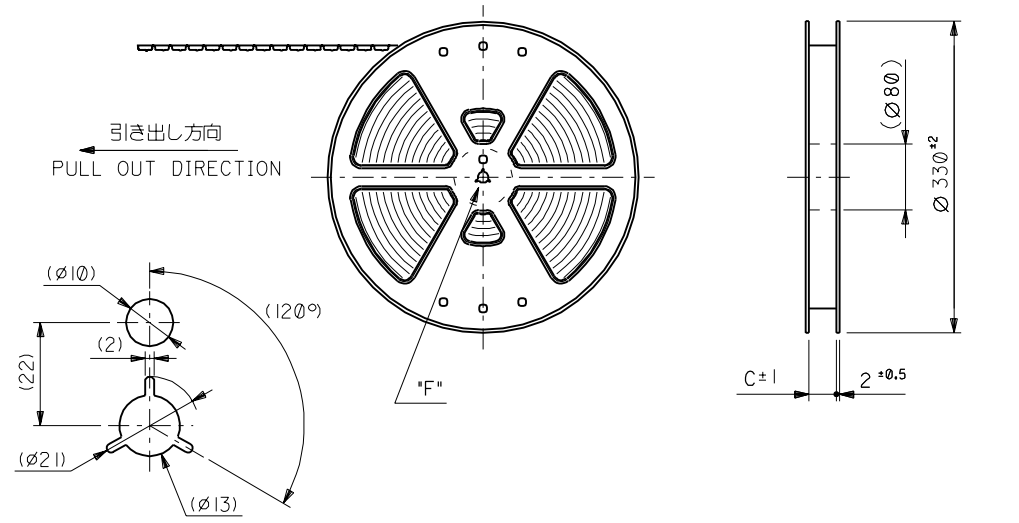
6

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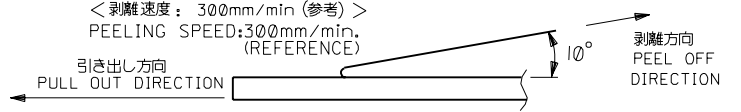
3

2



注記 NOTES

- 53261-\*\*\*10 の詳細寸法については図面 SD-53261-\*\*\*10 を参照下さい。  
RE DETAILED DIMENSIONS, SEE SD-53261-\*\*\*10.
- 梱包数量: 1000個/リール  
NUMBER OF CONNECTOR: 1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH  
 トップテープリーダー部 TOP TAPE LEADER PART 175 ± 25  
 トップテープ未接着部 TOP TAPE NON-BONDED PART 25 ± 5
- トップテープの剥離強度: 0.1N ~ 0.59N (10.2 ~ 60gf) (剥離方向は下図参照)  
PEELING OFF FORCE OF TOP TAPE: 0.1N ~ 0.59N (10.2 ~ 60gf)  
(PEELING DIRECTION IS SHOWN IN FOLLOWING FIG.)  
 <剥離速度: 300mm/min (参考)>  
PEELING SPEED: 300mm/min. (REFERENCE)
- 材料 (MATERIAL)  
 キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)  
 トップテープ (TOP TAPE): PET, PE, PEF  
 リール (REEL): ポリスチレン (PS) <リサイクル材含む>  
 POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>

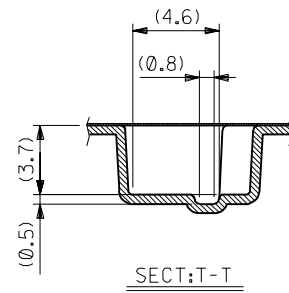
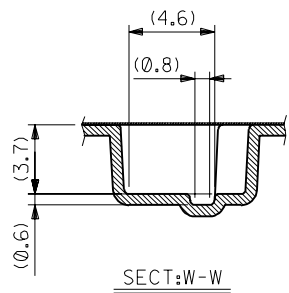
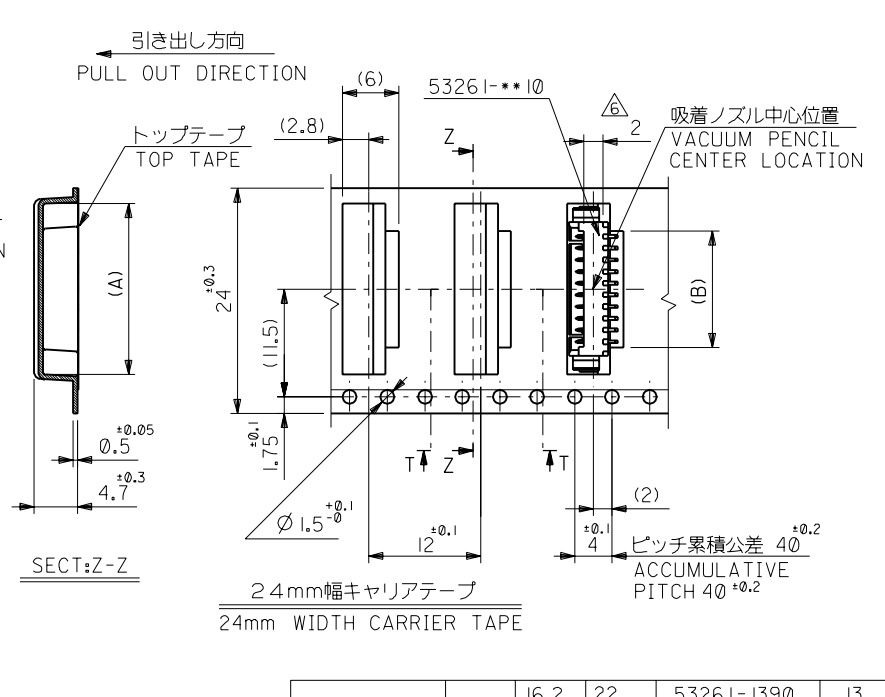
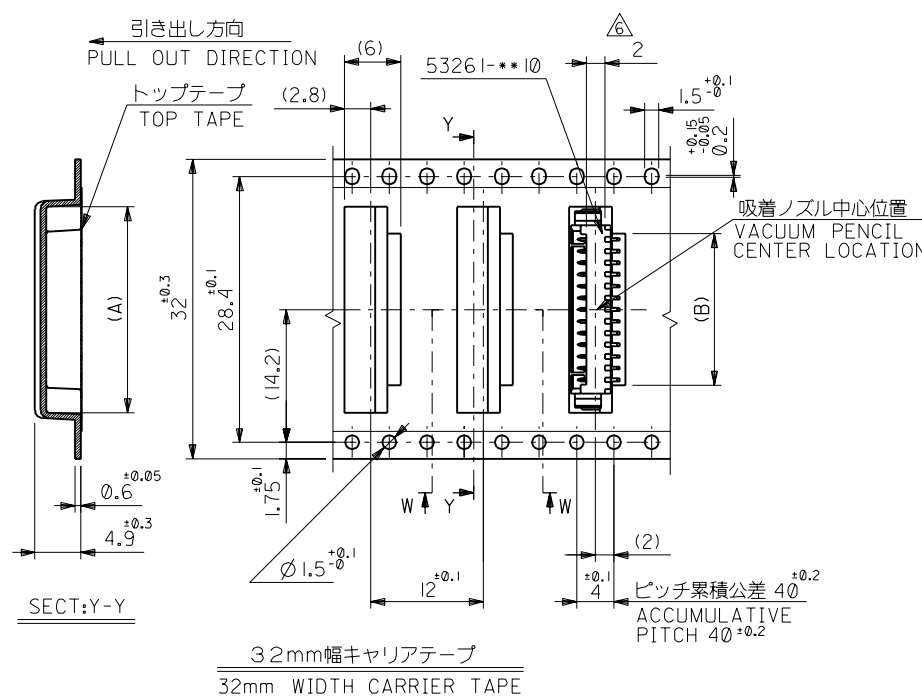


△ コネクタ、ハウジング平面部  
CONNECTOR, HOUSING FLAT AREA

16	16.4	3.7	9.5	53261-0390	3
キャリアテープ幅 CARRIER TAPE WIDTH	C	2.45	8.25	53261-0290	2
材料 MATERIAL	注記参照 SEE NOTES		molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社		
仕上げ FINISH	—		REVISE ONLY ON CAD SYSTEM		
適用電線範囲 WIRE RANGE	—		TITLE 名称 1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR SMT. EMBOSSED TAPE PACKAGE		
被覆外径 INS. RANGE	—		DWG. NO. SHEET 1 OF 3 REV SD-53261-***90		
DRAWN BY '93/6/1 K.TOJO	CHK'D BY '00/12/8 T.YAMAGUCHI	SCALE —			
APP'D BY '00/12/8 M.FUKUSHIMA	R. SCALE —				

角度 ANGLE	±3°				
30以上 OVER	+0.3				
10以上 30未満 OVER UNDER	+0.25	F	変更 REVISED	UC2001-0437H	S.M. T.Y '00/12/8
10未満 UNDER	+0.2	E	変更及び再作図 REVISED&REDRAWN	(J30522)	K.T. H.H '93/6/1
一般公差 GENERAL TOLERANCES		記号 LTR	変更内容 REVISION RECORD	DR. CHK.	日付 DATE

DWG. NO. SD-53261-\*\*\*90



32	32.4	16.2	22	53261-1390	13
		14.95	20.75	-1290	12
24	24.4	13.7	19.5	-1190	11
		12.45	18.25	-1090	10
		11.2	17	-0990	9
		9.95	15.75	-0890	8
		8.7	14.5	-0790	7
		7.45	13.25	-0690	6
		6.2	12	-0590	5
		4.95	10.75	53261-0490	4
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	A	ENG. NO.	極致 CKT.

角度 ANGLE	±3°				
30以上 OVER	+0.3				
10以上 30未満 UNDER	+0.25	F	変更 REVISED (02200110007)	S.M. T.Y	00/12/8
10未満 UNDER	+0.2	E	変更及び再作図 REVISED&REDRAWN (J30522)	K.T. H.H	93/6/1
一般公差 GENERAL TOLERANCES	記号 LTR	変更内容 REVISION RECORD	DR. CHK	日付 DATE	尺度 SCALE

材料 MATERIAL	注記参照 SEE NOTES	molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社
仕上げ FINISH	—	REVISE ONLY ON CAD SYSTEM
適用電線範囲 WIRE RANGE	—	TITLE 名称 I.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR SMT. EMBOSSD TAPE PACKAGE
被覆外径 INS. RANGE	—	DWG. NO. SHEET 2 OF 3 REV SD-53261-***90
		F

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX(JAPAN) AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION  
 本図面は日本モレックス(株)の所有する情報を含むもので 当社の許可なく複製を禁止する。 EN-01C(032)MXJ-32

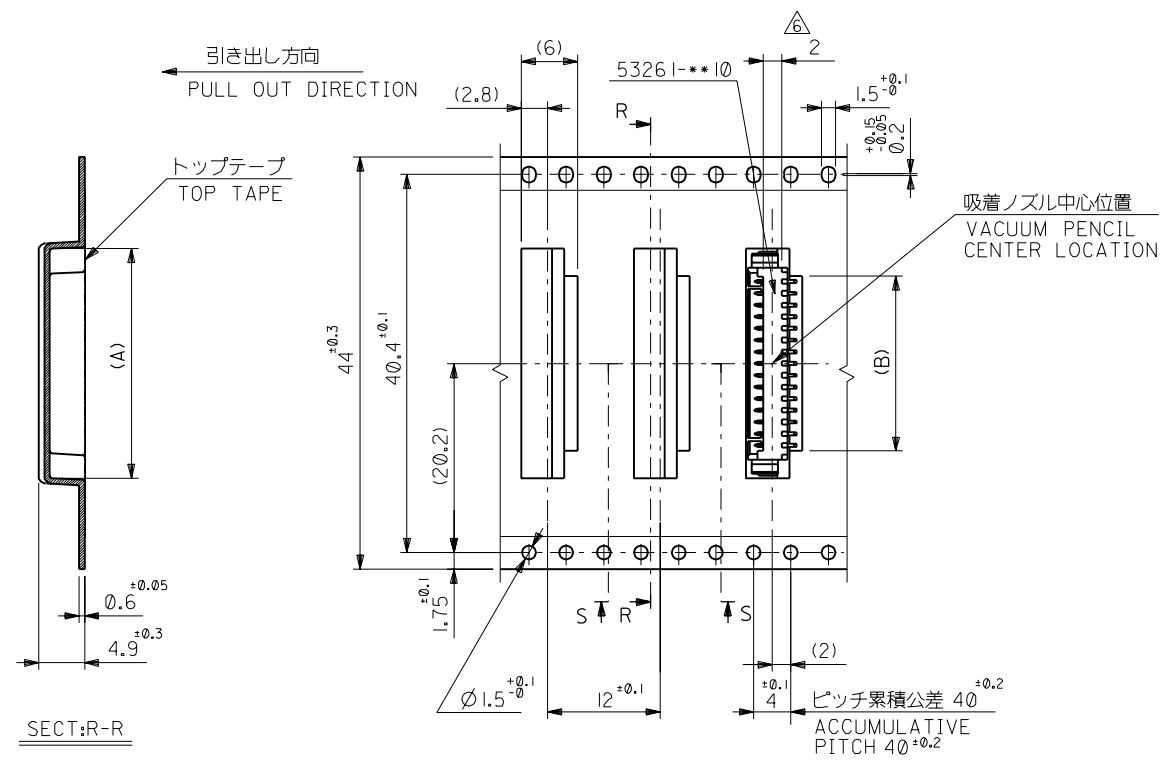
E

D

C  
B  
A  
DIMENSIONS IN METRIC DO NOT SCALE DRAWING

A

8 7 6 5 4 3 2 1



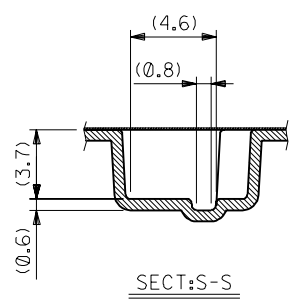
トップテープ  
TOP TAPE

吸着ノズル中心位置  
VACUUM PENCIL  
CENTER LOCATION

SECT:R-R

ピッチ累積公差 40  
ACCUMULATIVE  
PITCH 40

44mm幅キャリアテープ  
44mm WIDTH CARRIER TAPE

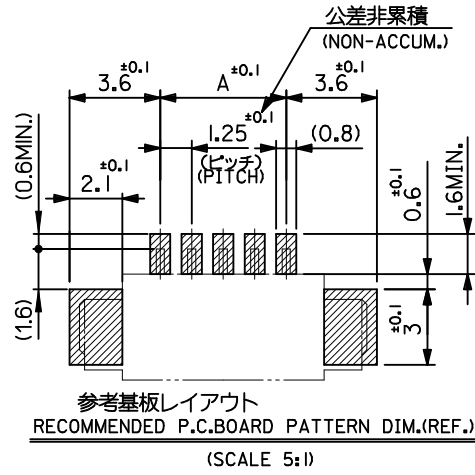
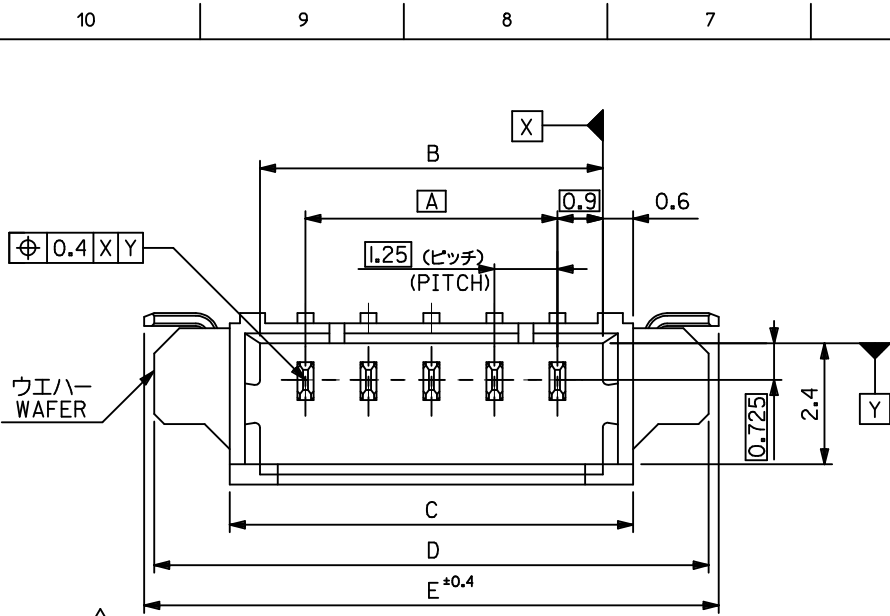


SECT:S-S

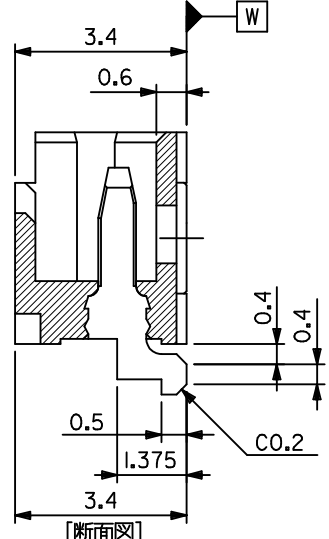
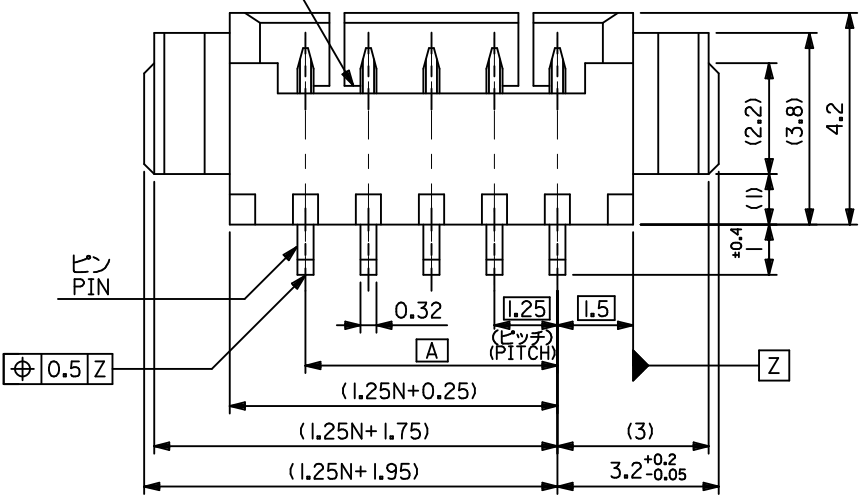
44	44.4	18.7	24.5	53261-1590	15
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	A	ENG. NO.	極致 CKT.
材料 MATERIAL	注記参照 SEE NOTES			molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
仕上げ FINISH	—			REVISE ONLY ON CAD SYSTEM	
適用電線範囲 WIRE RANGE	—			TITLE 名称 1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR SMT. EMBOSSD TAPE PACKAGE	
被覆外径 INS. RANGE	—			DWG. NO. SHEET 3 OF 3 REV SD-53261-***90	
DRAWN BY '93/6/1 K.TOJO	CHK'D BY '00/12/8 T.YAMAGUCHI	SCALE —			
APP'D BY '00/12/8 M.FUKUSHIMA	DATE				

角度 ANGLE	±3°				
30以上 OVER	±0.3				
10以上 30未満 OVER UNDER	±0.25	F	変更 REVISED (J30522)	S.M. T.Y	00/12/8
10未満 UNDER	±0.2	E	変更及び再作図 REVISED&REDRAWN (J30522)	K.T. H.H	'93/6/1
一般公差 GENERAL TOLERANCES		記号 LTR	変更内容 REVISION RECORD	DR. CHK	日付 DATE

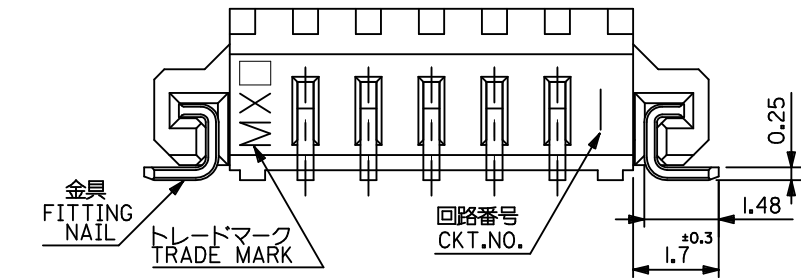
8 7 6 5 4 3 2 1



- 注記 NOTES**
1. 嵌合相手: 51021 シリウス  
MATES WITH: 51021 SERIES
  2. 材質 MATERIAL  
ウエハー: NYLON46, UL94V-0  
ピン: リン青銅, 半田メッキ  
PIN: PHOS-BRO., Sn-Pb(9:1) 3 μmMIN.  
OVER Cu 1 μmMIN.  
PLATING  
金具: リン青銅, 半田メッキ  
FITTING NAIL: PHOS-BRO., Sn-Pb(9:1) 2 μmMIN.  
OVER Cu 1 μmMIN.  
PLATING
  - △ ロック窓は2、3極は1箇所、4極以上は2箇所とする。  
LOCKING WINDOW: ONE PLACE FOR 2 AND 3 CKT. AND TWO PLACES FOR MORE THAN 3 CKT.
  4. ソルダータール部のズレ量及び金具(補強板)のズレ量は基準面[W]に対し、上方向0.05 MAX.、下方向に0.1 MAX.とする。  
OFFSET BETWEEN BASIS PLANE [W] TO SOLDER TAIL BOTTOM AND FITTING NAIL BOTTOM: UPPER SIDE: 0.05MAX. LOWER SIDE: 0.1MAX.



23.9	23.5	20.5	19.3	17.5	53261-1510	15
22.65	22.25	19.25	18.05	16.25	-1410	14
21.4	21	18	16.8	15	-1310	13
20.15	19.75	16.75	15.55	13.75	-1210	12
18.9	18.5	15.5	14.3	12.5	-1110	11
17.65	17.25	14.25	13.05	11.25	-1010	10
16.4	16	13	11.8	10	-0910	9
15.15	14.75	11.75	10.55	8.75	-0810	8
13.9	13.5	10.5	9.3	7.5	-0710	7
12.65	12.25	9.25	8.05	6.25	-0610	6
11.4	11	8	6.8	5	-0510	5
10.15	9.75	6.75	5.55	3.75	-0410	4
8.9	8.5	5.5	4.3	2.5	-0310	3
7.65	7.25	4.25	3.05	1.25	53261-0210	2
E	D	C	B	A	ENG. NO.	極数 CKT.



REVISED EC NO: J2012-1315 2012/04/17  
 DRWN: NITO 2012/04/17  
 CHKD: KASAKAWA 2012/04/17  
 APPR: YOITO 2012/04/26

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DESCRIPTION: DIMENSION STYLE: MM ONLY  
 SCALE: 10:1  
 DESIGN UNITS: METRIC  
 THIRD ANGLE PROJECTION

DRAWN BY: NITO DATE: 2012/04/17  
 CHECKED BY: KASAKAWA DATE: 2012/04/17  
 APPROVED BY: YOITO DATE: 2012/04/26

MATERIAL NO.: SEE DRAWING  
 DOCUMENT NO.: SD-53261-054  
 SHEET NO.: 1 OF 1

1.25 WIRE TO BOARD WAFER ASS FOR SMT RIGHT ANGLE

**molex**

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